



# FDWS9508L!F085

## P-Channel PowerTrench® MOSFET

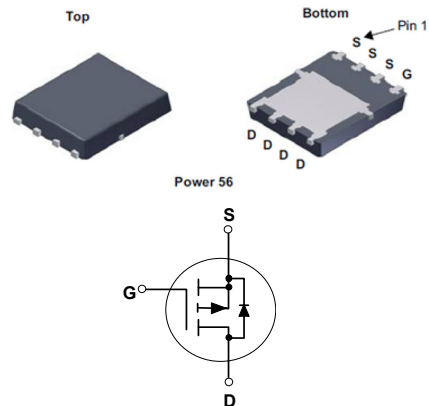
- 40 V, - 80 A, 4.9 mΩ

### Features

- Typical  $R_{DS(on)}$  = 3.6 mΩ at  $V_{GS} = -10V$ ,  $I_D = -80 A$
- Typical  $Q_{g(tot)}$  = 82 nC at  $V_{GS} = -10V$ ,  $I_D = -80 A$
- UIS Capability
- RoHS Compliant
- Qualified to AEC Q101
- Wettable flanks for automatic optical inspection (AOI)

### Applications

- Automotive Engine Control
- PowerTrain Management
- Solenoid and Motor Drivers
- Electrical Power Steering
- Integrated Starter/Alternator
- Distributed Power Architectures and VRM
- Primary Switch for 12V Systems



### MOSFET Maximum Ratings $T_J = 25^\circ\text{C}$ unless otherwise noted.

Symbol	Parameter	Ratings	Units
$V_{DSS}$	Drain-to-Source Voltage	-40	V
$V_{GS}$	Gate-to-Source Voltage	±16	V
$I_D$	Drain Current - Continuous ( $V_{GS} = -10$ ) (Note 1)	$T_C = 25^\circ\text{C}$	A
	Pulsed Drain Current	$T_C = 25^\circ\text{C}$	
$E_{AS}$	Single Pulse Avalanche Energy (Note 2)	211	mJ
$P_D$	Power Dissipation	214	W
	Derate Above $25^\circ\text{C}$	1.43	W/ $^\circ\text{C}$
$T_J, T_{STG}$	Operating and Storage Temperature	-55 to + 175	$^\circ\text{C}$
$R_{\theta JC}$	Thermal Resistance, Junction to Case	0.7	$^\circ\text{C/W}$
$R_{\theta JA}$	Maximum Thermal Resistance, Junction to Ambient (Note 3)	50	$^\circ\text{C/W}$

#### Notes:

- 1: Current is limited by wirebond configuration.
- 2: Starting  $T_J = 25^\circ\text{C}$ ,  $L = 0.1\text{mH}$ ,  $I_{AS} = -65\text{A}$ ,  $V_{DD} = -40\text{V}$  during inductor charging and  $V_{DD} = 0\text{V}$  during time in avalanche.
- 3:  $R_{\theta JA}$  is the sum of the junction-to-case and case-to-ambient thermal resistance, where the case thermal reference is defined as the solder mounting surface of the drain pins.  $R_{\theta JC}$  is guaranteed by design, while  $R_{\theta JA}$  is determined by the board design. The maximum rating presented here is based on mounting on a 1 in<sup>2</sup> pad of 2oz copper.

### Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDWS9508L	FDWS9508L!F085	Power56	13"	12mm	3000 units

**Electrical Characteristics**  $T_J = 25^\circ\text{C}$  unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
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**Off Characteristics**

$B_{V_{DS}}$	Drain-to-Source Breakdown Voltage	$I_D = -250\mu\text{A}$ , $V_{GS} = 0\text{V}$	-40	-	-	V
$I_{DSS}$	Drain-to-Source Leakage Current	$V_{DS} = -40\text{V}$ , $T_J = 25^\circ\text{C}$ $V_{GS} = 0\text{V}$ , $T_J = 175^\circ\text{C}$ (Note 4)	-	-	-1	$\mu\text{A}$ mA
$I_{GSS}$	Gate-to-Source Leakage Current	$V_{GS} = \pm 16\text{V}$ , $V_{DS} = 0\text{V}$	-	-	$\pm 100$	nA

**On Characteristics**

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}$ , $I_D = -250\mu\text{A}$	-1.0	-1.8	-3.0	V
$R_{DS(on)}$	Drain to Source On Resistance	$I_D = -80\text{A}$ , $V_{GS} = -4.5\text{V}$ , $T_J = 25^\circ\text{C}$	-	5.6	8.5	$\text{m}\Omega$
		$I_D = -80\text{A}$ , $T_J = 25^\circ\text{C}$	-	3.6	4.9	$\text{m}\Omega$
		$V_{GS} = -10\text{V}$ , $T_J = 175^\circ\text{C}$ (Note 4)	-	5.9	8.0	$\text{m}\Omega$

**Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = -20V, V <sub>GS</sub> = 0V, f = 1MHz		-	4840	-	pF
C <sub>oss</sub>	Output Capacitance			-	2310	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance			-	49	-	pF
R <sub>g</sub>	Gate Resistance	f = 1MHz		-	24	-	Ω
Q <sub>g(ToT)</sub>	Total Gate Charge at 10V	V <sub>GS</sub> = 0 to -10V	V <sub>DD</sub> = -32V I <sub>D</sub> = -80A	-	82	107	nC
Q <sub>g(th)</sub>	Threshold Gate Charge	V <sub>GS</sub> = 0 to -2V		-	11	-	nC
Q <sub>gs</sub>	Gate-to-Source Gate Charge			-	20	-	nC
Q <sub>gd</sub>	Gate-to-Drain “Miller” Charge			-	10	-	nC

**Switching Characteristics**

$t_{on}$	Turn-On Time	$V_{DD} = -20\text{V}$ , $I_D = -80\text{A}$ , $V_{GS} = -10\text{V}$ , $R_{GEN} = 6\Omega$	-	-	23	ns
$t_{d(on)}$	Turn-On Delay		-	10	-	ns
$t_r$	Rise Time		-	5	-	ns
$t_{d(off)}$	Turn-Off Delay		-	389	-	ns
$t_f$	Fall Time		-	114	-	ns
$t_{off}$	Turn-Off Time		-	-	780	ns

**Drain-Source Diode Characteristics**

$V_{SD}$	Source-to-Drain Diode Voltage	$I_{SD} = -80\text{A}$ , $V_{GS} = 0\text{V}$	-	-	-1.25	V
		$I_{SD} = -40\text{A}$ , $V_{GS} = 0\text{V}$	-	-	-1.2	V
$t_{rr}$	Reverse-Recovery Time	$I_{SD} = -80\text{A}$ , $dI_{SD}/dt = 100\text{A}/\mu\text{s}$ , $V_{DD} = -32\text{V}$	-	82	107	ns
$Q_{rr}$	Reverse-Recovery Charge		-	95	124	nC

**Note:**

4: The maximum value is specified by design at  $T_J = 175^\circ\text{C}$ . Product is not tested to this condition in production.

## Typical Characteristics

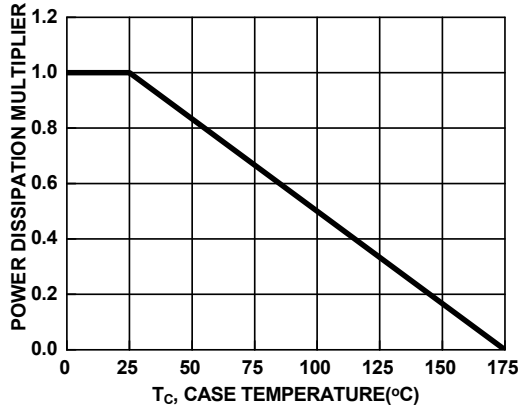


Figure 1. Normalized Power Dissipation vs. Case Temperature

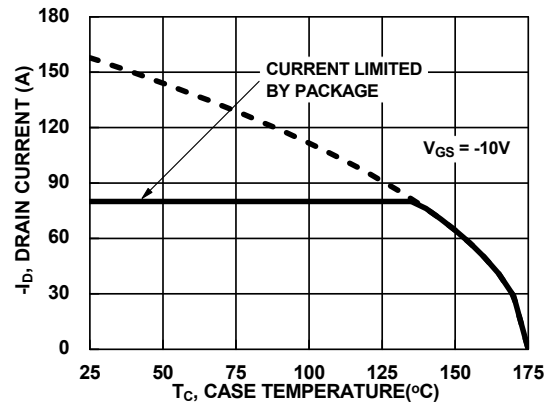


Figure 2. Maximum Continuous Drain Current vs. Case Temperature

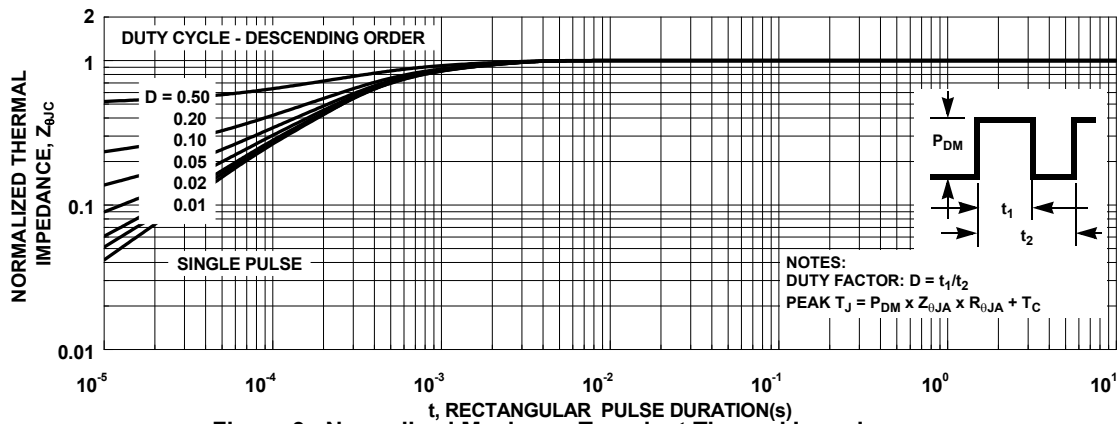


Figure 3. Normalized Maximum Transient Thermal Impedance

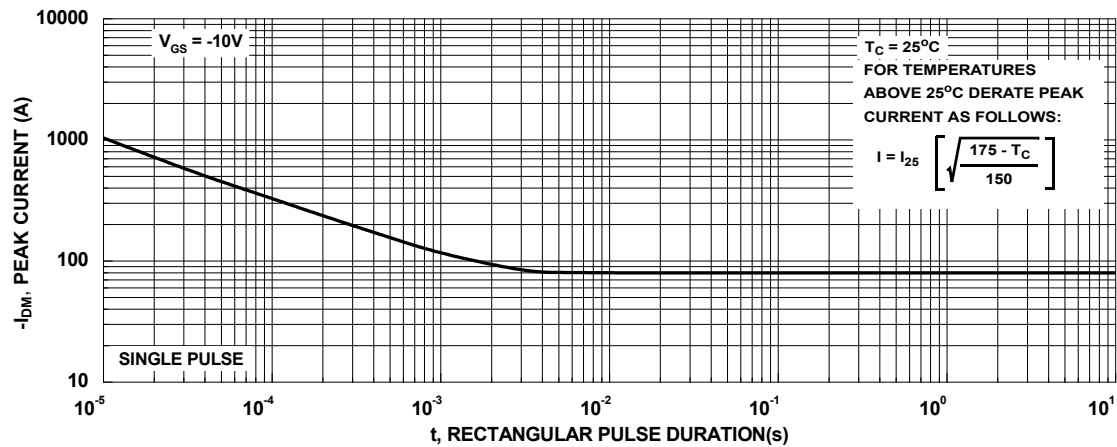


Figure 4. Peak Current Capability

## Typical Characteristics

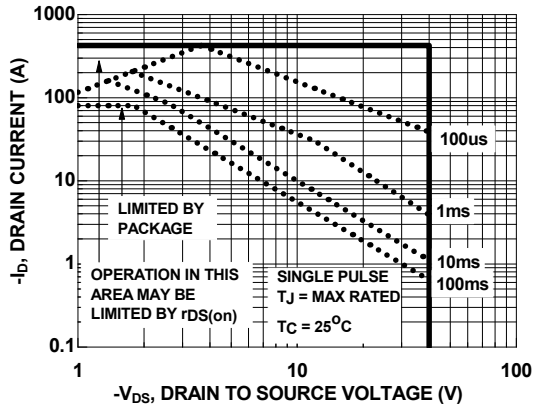
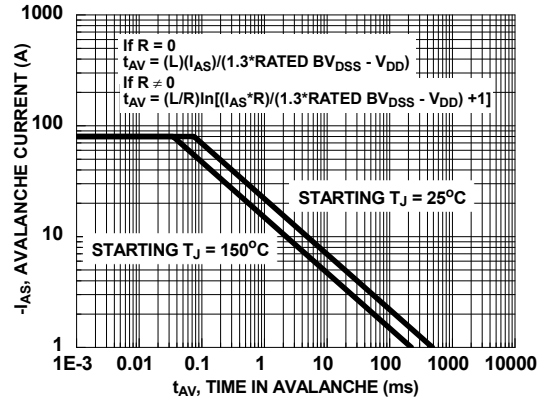


Figure 5. Forward Bias Safe Operating Area



NOTE: Refer to Fairchild Application Notes AN7514 and AN7515

Figure 6. Unclamped Inductive Switching Capability

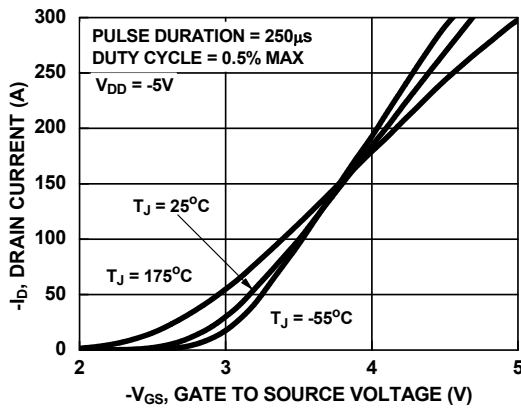


Figure 7. Transfer Characteristics

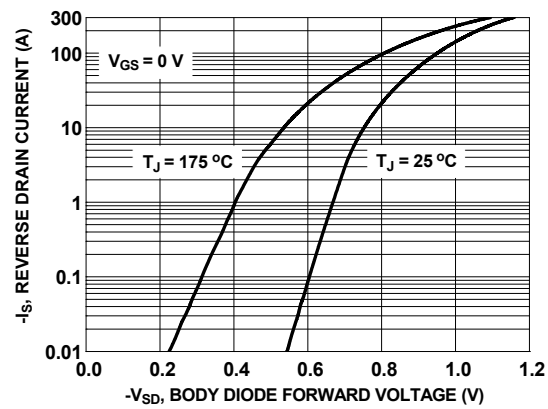


Figure 8. Forward Diode Characteristics

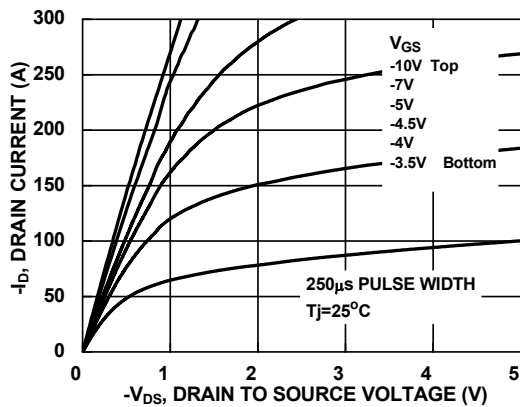


Figure 9. Saturation Characteristics

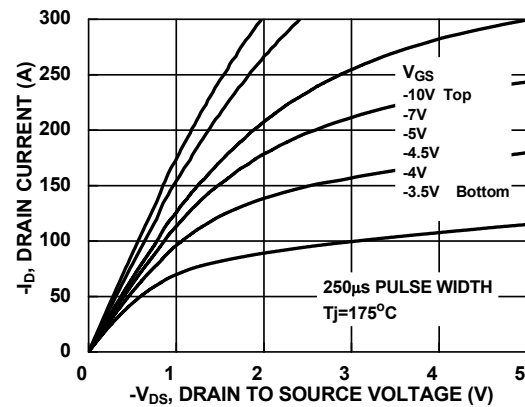


Figure 10. Saturation Characteristics

## Typical Characteristics

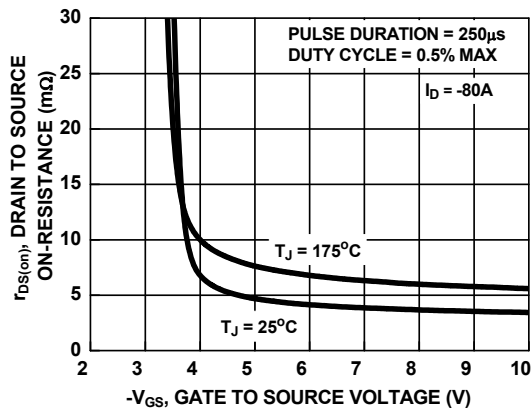


Figure 11.  $R_{DS(on)}$  vs. Gate Voltage

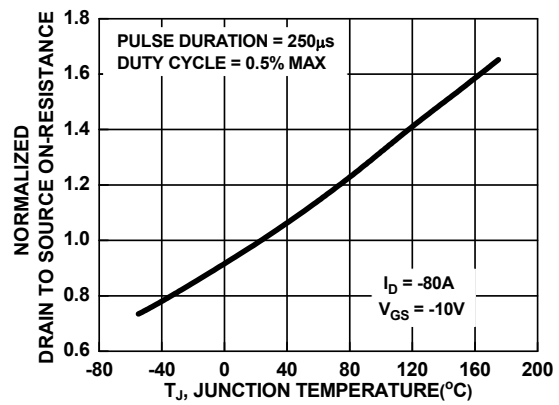


Figure 12. Normalized  $R_{DS(on)}$  vs. Junction Temperature

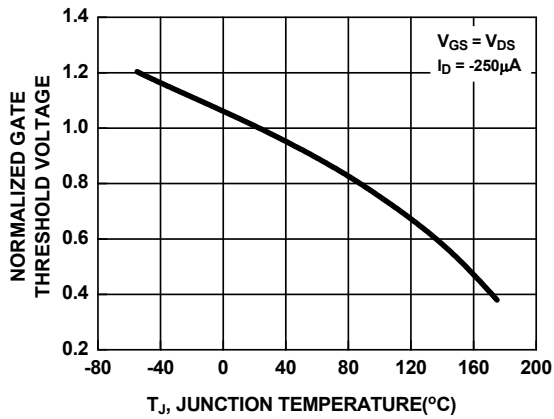


Figure 13. Normalized Gate Threshold Voltage vs. Temperature

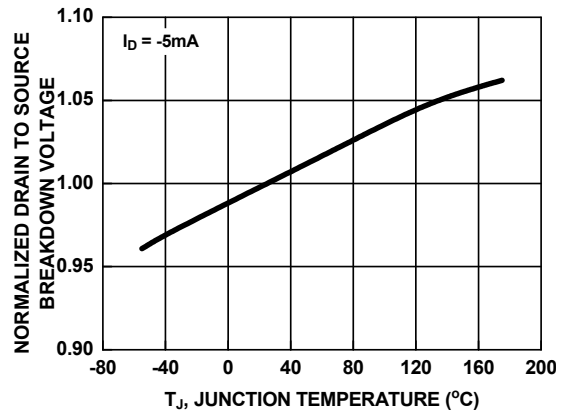


Figure 14. Normalized Drain to Source Breakdown Voltage vs. Junction Temperature

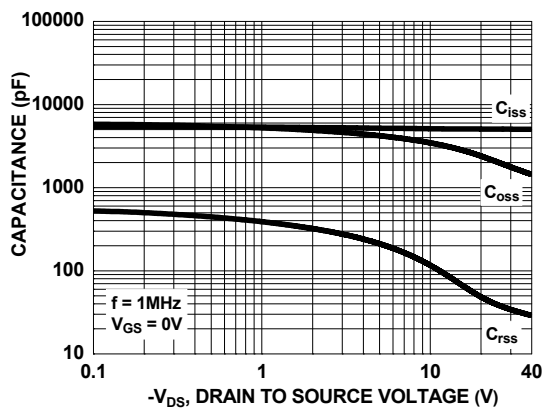


Figure 15. Capacitance vs. Drain to Source Voltage

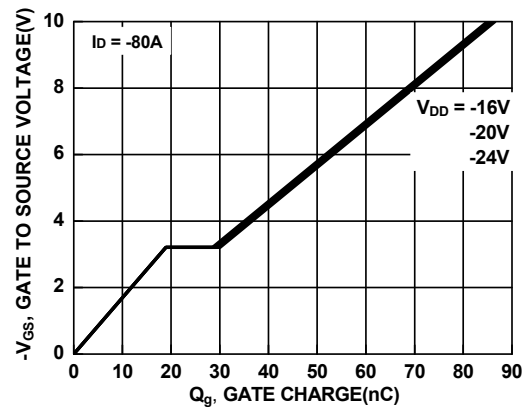
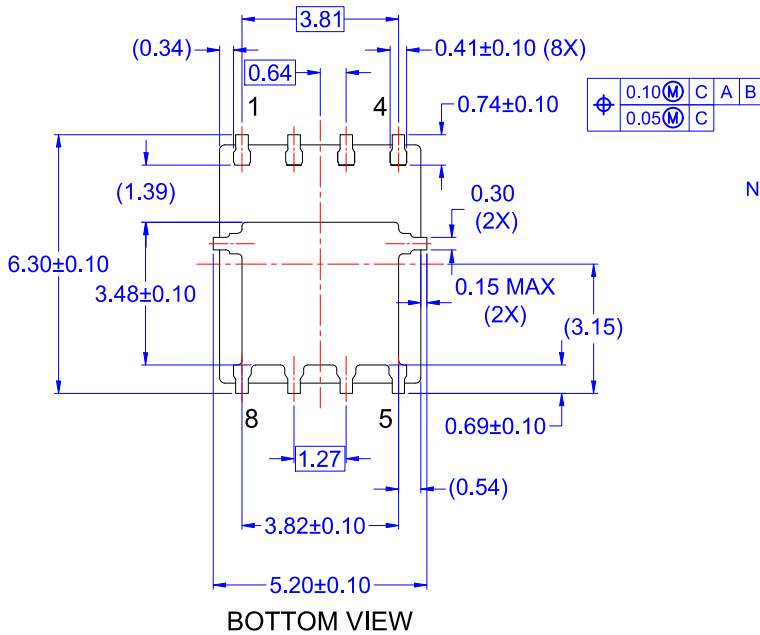
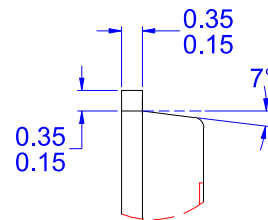
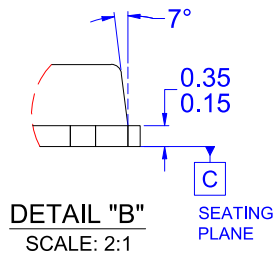
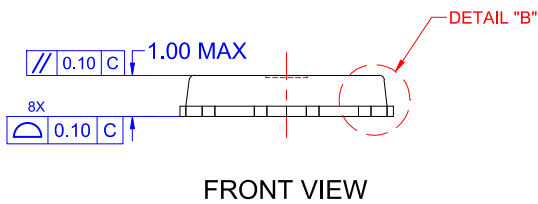
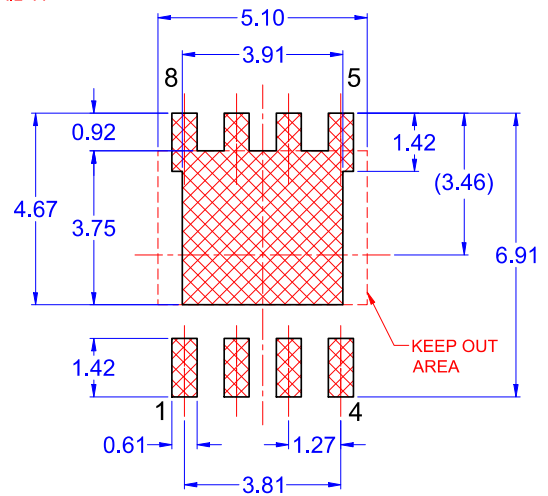
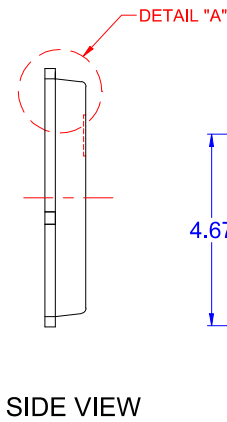
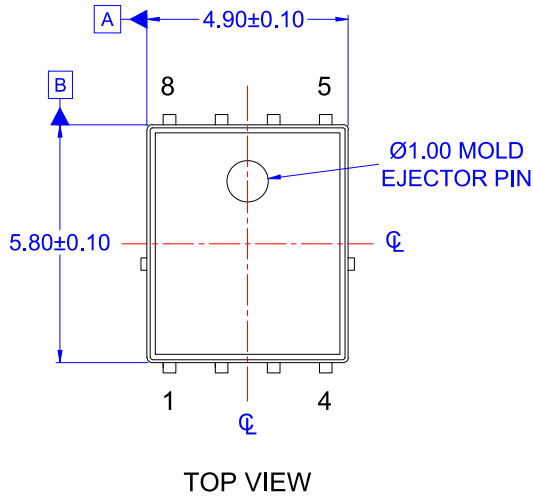



Figure 16. Gate Charge vs. Gate to Source Voltage

PACKAGE DIMENSIONS

PQFN8 5X6, 1.27P  
CASE 483BJ  
ISSUE B



- NOTES: UNLESS OTHERWISE SPECIFIED
- A) PACKAGE STANDARD REFERENCE:  
JEDEC REGISTRATION, MO-240.
  - B) ALL DIMENSIONS ARE IN MILLIMETERS.
  - C) DIMENSIONS DO NOT INCLUDE BURRS OR  
MOLD FLASH. MOLD FLASH OR BURRS  
DOES NOT EXCEED 0.10MM.
  - D) IT IS RECOMMENDED TO HAVE NO TRACES  
OR VIAS WITHIN THE KEEP OUT AREA.

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